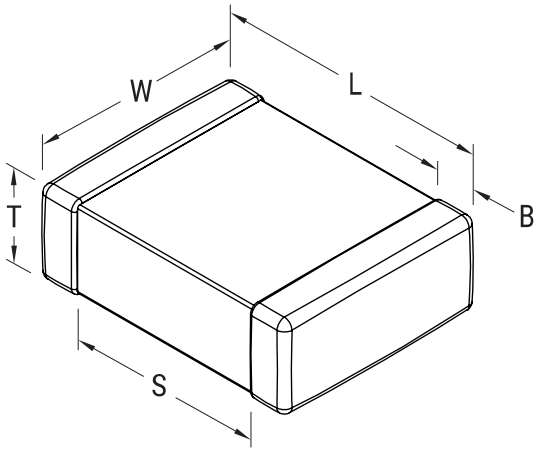
C1808C332JBGACTU

Aliases (C1808C332JBGAC7800)

SMD Comm C0G HV, Ceramic, 3,300 pF, 5%, 630 VDC, C0G, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 1808, 2.9 mm



Click here for the 3D model.

General Information	
Series	SMD Comm C0G HV
Style	SMD Chip
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	62 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1808
L	4.7mm +/-0.5mm
W	2mm +/-0.2mm
T	1.4mm +/-0.15mm
S	2.9mm MIN
B	0.6mm +/-0.35mm

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	1000

Specifications	
Capacitance	3,300 pF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	5%
Voltage DC	630 VDC
Dielectric Withstanding Voltage	945 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	C0G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms